

09/365,356

L Number	Hits	Search Text	DB	Time stamp
1	2791	((257/701) or (438/125) or (438/118)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:57
2	1638	((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 14:58
3	321	(((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730). and (adhesiv\$3 adher\$3) and (interposer carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 15:00
4	22	(((((257/701) or (438/125) or (438/118)).CCLS.) and @ad<19990730) and (strip near4 (adhesiv\$3 adher\$3)) and (interposer carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 15:09
5	1266	(interposer carrier) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 15:11
6	30	((polyimide organic) near4 (interposer carrier)) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 15:11
7	100	((polyimide organic) near4 (interposer carrier substrate)) and @ad<19990730 and (strip near3 (adher\$3 adhesiv\$3)) and (semiconductor chip die dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/23 15:12